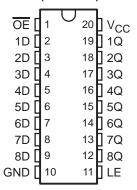
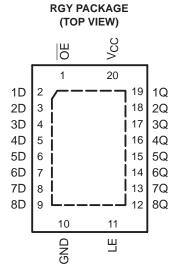
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- Inputs Are TTL-Voltage Compatible
- 4.5-V to 5.5-V V_{CC} Operation
- Typical t_{pd} = 5.1 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 5 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2.3 V at V_{CC} = 5 V, T_A = 25°C
- Supports Mixed-Mode Voltage Operation on All Ports

DB, DGV, DW, NS, OR PW PACKAGE (TOP VIEW)



- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)



description/ordering information

The SN74LV573AT is an octal transparent D-type latch. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is low, the Q outputs are latched at the logic levels of the D inputs.

ORDERING INFORMATION

TA	PACKA	GEŤ	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	QFN – RGY	Tape and reel	SN74LV573ATRGYR	LV573AT
	COIC DW	Tube	SN74LV573ATDW	1)/570AT
	SOIC - DW	Tape and reel	SN74LV573ATDWR	LV573AT
-40°C to 85°C	SOP – NS	Tape and reel	SN74LV573ATNSR	74LV573AT
-40 C to 65 C	SSOP – DB	Tape and reel	SN74LV573ATDBR	LV573AT
		Tube	SN74LV573ATPW	1)/570AT
	TSSOP – PW	Tape and reel	SN74LV573ATPWR	LV573AT
	TVSOP - DGV	Tape and reel	SN74LV573ATDGVR	LV573AT

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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description/ordering information (continued)

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

To ensure the high-impedance state during power up or power down, \overline{OE} shall be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

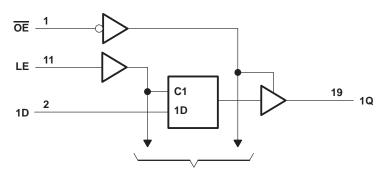
OE does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

FUNCTION TABLE (each latch)

	OUTPUT		
OE	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	Q ₀
Н	X	Χ	Z

logic diagram (positive logic)



To Seven Other Channels

SN74LV573AT OCTAL TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	
Voltage range applied to any output in the high-impedance or power-off state, V _O (see Note 1)	
Input clamp current, I_{IK} ($V_I < 0$)	
Output clamp current, I _{OK} (V _O < 0)	
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±35 mA
Continuous current through V _{CC} or GND	±70 mA
Package thermal impedance, θ _{JA} (see Note 3): DB package	70°C/W
(see Note 3): DGV package	92°C/W
(see Note 3): DW package	58°C/W
(see Note 3): NS package	60°C/W
(see Note 3): PW package	
(see Note 4): RGY package	
Storage temperature range, T _{stq}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 5.5 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.
 - 4. The package thermal impedance is calculated in accordance with JESD 51-5.

recommended operating conditions (see Note 5)

			MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	V
VIH	High-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	2		V
VIL	Low-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		0.8	V
VI	Input voltage		0	5.5	V
.,	Outside will a me	High or low state	0	VCC	
VO	Output voltage	3-state	0	5.5	V
ЮН	High-level output current	V _{CC} = 4.5 V to 5.5 V		-16	mA
loL	Low-level output current	V _{CC} = 4.5 V to 5.5 V		16	mA
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		20	ns/V
TA	Operating free-air temperature		-40	85	°C

NOTE 5: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SN74LV573AT OCTAL TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Vcc	т,	4 = 25°C	;	T _A = -		UNIT
			MIN	TYP	MAX	MIN	MAX	
V	$I_{OH} = -50 \mu\text{A}$	4.5 V	4.4	4.5		4.4		V
Voн	I _{OH} = −16 mA	4.5 V	3.8			3.8		V
\/ - ·	I _{OL} = 50 μA	4.5 V		0	0.1		0.1	V
VOL	I _{OL} = 16 mA	4.5 V			0.55		0.55	V
lį	V _I = 5.5 V or GND	0 to 5.5 V			±0.1		±1	μΑ
loz	$V_O = V_{CC}$ or GND	5.5 V			±0.25		±2.5	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			2		20	μΑ
∆lcc†	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			1.35		1.5	mA
l _{off}	V_I or $V_O = 0$ to 5.5 V	0			0.5		5	μΑ
C _i	$V_I = V_{CC}$ or GND			4.5	·		·	pF

[†] This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or VCC.

timing requirements over recommended operating free-air temperature range, V $_{\rm CC}$ = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

		T _A =	25°C	T _A = -40°C TO 85°C		UNIT
		MIN	MAX	MIN	MAX	
t _W	Pulse duration, LE high	6.5		8.5		ns
t _{su}	Setup time, data before LE↓	1.5		1.5		ns
th	Hold time, data after LE↓	3.5		3.5		ns



switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO	LOAD	T,	Δ = 25°C	;	T _A = -		UNIT
	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	
tPLH	2	0	0 45 -5	2.6	5.1	8.5	1	9.5	
^t PHL	D	Q	C _L = 15 pF	3	5.1	8.5	1	9.5	ns
tPLH		0	C. 15 pF	3	7.7	12.3	1	14.5	20
^t PHL	LE	Q	C _L = 15 pF	3.5	7.7	12.3	1	14.5	ns
^t PZH	<u>OE</u>	0	0. 45.5	3	6.3	10.9	1	12.5	
t _{PZL}	OE	Q	C _L = 15 pF	3.3	6.3	10.9	1	12.5	ns
t _{PHZ}	<u>OE</u>	•	0 455	2.8	5.5	8	1	11	
tPLZ	OE	Q	C _L = 15 pF	1.6	5.4	8	1	9.5	ns
^t PLH	D	0	C. F0.5F	3.7	5.9	9.5	1	10.5	20
^t PHL	U	Q	$C_L = 50 pF$	5.5	5.9	9.5	1	10.5	ns
t _{PLH}	LE	0	C: 50 = 5	4.3	8.5	13.3	1	14.5	
t _{PHL}	LE	Q	C _L = 50 pF	5.9	8.5	13.3	1	14.5	ns
^t PZH	<u>OE</u>	•	0 50 - 5	4.5	7.1	11.9	1	13.5	
tPZL	OE	Q	C _L = 50 pF	5.4	7.1	11.9	1	13.5	ns
^t PHZ	ŌĒ	0	C. F0.pF	3.3	8.8	11.2	1	12	20
tPLZ	ÜE	Q	$C_L = 50 pF$	2.6	8.8	11.2	1	12	ns
tsk(o)			C _L = 50 pF			1.5		1.5	ns

noise characteristics, $V_{CC} = 5 \text{ V}$, $C_L = 50 \text{ pF}$ (see Note 6)

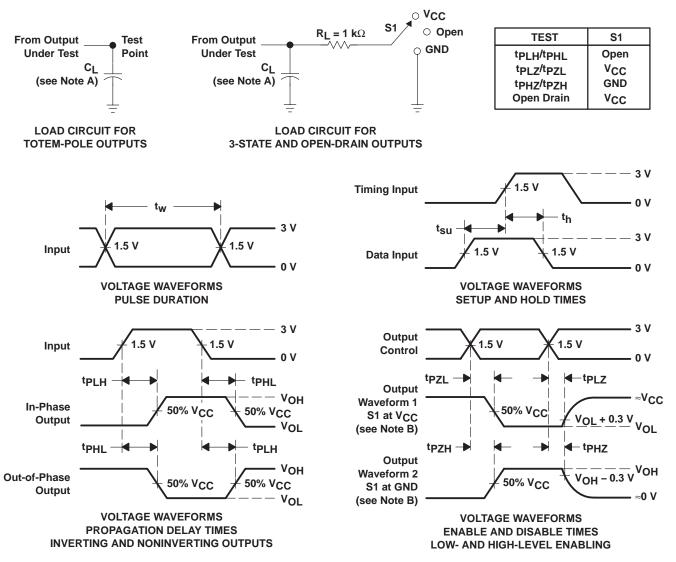
DADAMETED		T _A = 25°C			LINUT
	PARAMETER		TYP	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		1.1	1.5	V
V _{OL} (V)	Quiet output, minimum dynamic V _{OL}		-1.1	-1.5	V
V _{OH(V)}	Quiet output, minimum dynamic V _{OH}		4		V
V _{IH(D)}	High-level dynamic input voltage	2			V
V _{IL(D)}	Low-level dynamic input voltage			0.8	V

NOTE 6: Characteristics are for surface-mount packages only.

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

PARAMETER		TEST CO	TYP	UNIT		
C _{pd}	Power dissipation capacitance	Outputs enabled	$C_L = 50 \text{ pF},$	f = 10 MHz	8	pF

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_Q = 50 \Omega$, $t_f \leq 3$ ns, $t_f \leq 3$ ns.
 - D. The outputs are measured one at a time, with one input transition per measurement.
 - E. tpLZ and tpHZ are the same as tdis.
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. tpHL and tpLH are the same as tpd.
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuits and Voltage Waveforms



DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



DW (R-PDSO-G20)

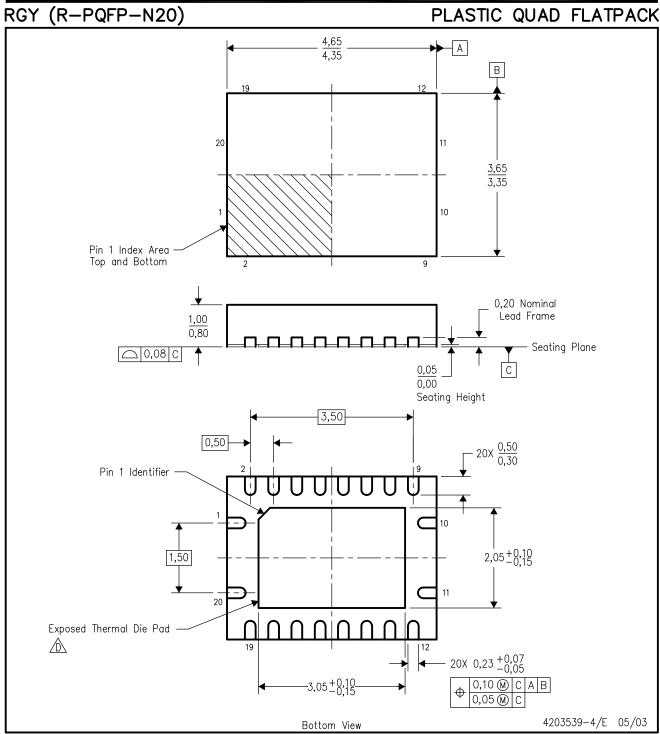
PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.





NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. QFN (Quad Flatpack No-Lead) package configuration.
- The package thermal performance may be enhanced by bonding the thermal die pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected ground leads.
- E. Package complies to JEDEC MO-241 variation BC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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